



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0802NLS	Issued	12. August 2021
MA#	MA005625440		
Package	PG-TDSON-8-50	Weight*	107.28 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.457	1.36	1.36	13584	13584
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		127	
	non noble metal	zinc	7440-66-6	0.055	0.05		508	
	non noble metal	iron	7439-89-6	1.090	1.02		10163	
	non noble metal	copper	7440-50-8	44.271	41.26	42.34	412660	423458
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	400	400
encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		778	
	plastics	epoxy resin	-	3.842	3.58		35808	
	inorganic material	silicondioxide	60676-86-0	37.831	35.26	38.92	352628	389214
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11779	11779
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	270	270
solder	noble metal	silver	7440-22-4	0.050	0.05		462	
	non noble metal	tin	7440-31-5	0.099	0.09		925	
	non noble metal	lead	7439-92-1	1.835	1.71	1.85	17104	18491
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		171	
	non noble metal	iron	7439-89-6	0.368	0.34		3427	
	non noble metal	copper	7440-50-8	14.930	13.92	14.28	139163	142804
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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